



# STD100NH03L

## N-CHANNEL 30V - 0.005 Ω - 60A DPAK STripFET™ III POWER MOSFET

TYPE	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
STD100NH03L	30 V	< 0.0055 Ω	60 A(2)

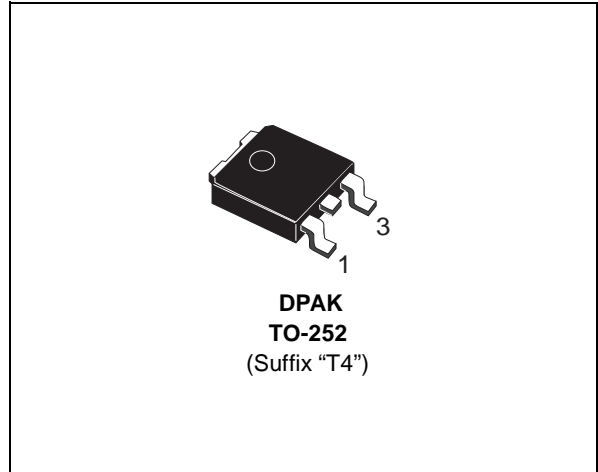
- TYPICAL R<sub>DS(on)</sub> = 0.005 Ω @ 10 V
- R<sub>DS(ON)</sub> \* Qg INDUSTRY'S BENCHMARK
- CONDUCTION LOSSES REDUCED
- SWITCHING LOSSES REDUCED
- LOW THRESHOLD DEVICE
- SURFACE-MOUNTING DPAK (TO-252)  
POWER PACKAGE IN TAPE & REEL  
(SUFFIX "T4")

### DESCRIPTION

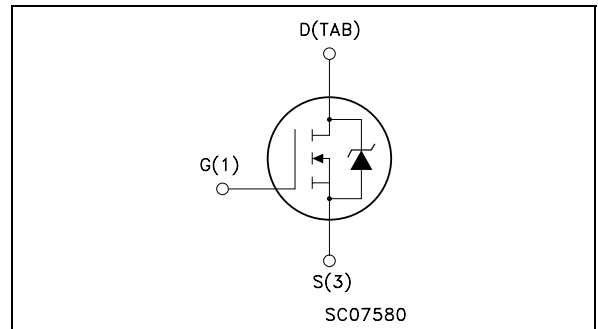
The **STD100NH03L** utilizes the latest advanced design rules of ST's proprietary STripFET™ technology. This is suitable for the most demanding DC-DC converter application where high efficiency is to be achieved.

### APPLICATIONS

- SPECIFICALLY DESIGNED AND OPTIMISED FOR HIGH EFFICIENCY DC/DC CONVERTERS



### INTERNAL SCHEMATIC DIAGRAM



### Ordering Information

SALES TYPE	MARKING	PACKAGE	PACKAGING
STD100NH03LT4	D100NH03L	TO-252	TAPE & REEL

### ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	30	V
V <sub>DGR</sub>	Drain-gate Voltage (R <sub>GS</sub> = 20 kΩ)	30	V
V <sub>GS</sub>	Gate- source Voltage	± 20	V
I <sub>D</sub> (2)	Drain Current (continuous) at T <sub>C</sub> = 25°C	60	A
I <sub>D</sub> (2)	Drain Current (continuous) at T <sub>C</sub> = 100°C	60	A
I <sub>DM</sub> (3)	Drain Current (pulsed)	240	A
P <sub>tot</sub>	Total Dissipation at T <sub>C</sub> = 25°C	100	W
	Derating Factor	0.66	W/°C
E <sub>AS</sub> (4)	Single Pulse Avalanche Energy	700	mJ
T <sub>stg</sub>	Storage Temperature	-55 to 175	°C
T <sub>j</sub>	Max. Operating Junction Temperature		

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## THERMAL DATA

Rthj-case	Thermal Resistance Junction-case	Max	1.5	°C/W
Rthj-amb	Thermal Resistance Junction-ambient	Max	100	°C/W
Rthj-pcb	Thermal Resistance Junction-pcb(#)	Max	43	°C/W
T <sub>I</sub>	Maximum Lead Temperature For Soldering Purpose		275	°C

(#) When Mounted on 1 inch<sup>2</sup> FR-4 board, 2 oz of Cu.

## ELECTRICAL CHARACTERISTICS (T<sub>CASE</sub> = 25 °C UNLESS OTHERWISE SPECIFIED)

### OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown Voltage	I <sub>D</sub> = 250 μA, V <sub>GS</sub> = 0	30			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = Max Rating V <sub>DS</sub> = Max Rating T <sub>C</sub> = 125°C			1 10	μA μA
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 20V			±100	nA

### ON (\*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> I <sub>D</sub> = 250 μA	1	1.8	2.5	V
R <sub>DS(on)</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 10 V I <sub>D</sub> = 30 A V <sub>GS</sub> = 5 V I <sub>D</sub> = 30 A		0.005 0.0060	0.0055 0.0105	Ω Ω

## DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g <sub>fs</sub> (5)	Forward Transconductance	V <sub>DS</sub> = 10 V I <sub>D</sub> = 30 A		40		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V <sub>DS</sub> = 15V f = 1 MHz V <sub>GS</sub> = 0		4100 680 70		pF pF pF
R <sub>G</sub>	Gate Input Resistance	f = 1 MHz Gate DC Bias = 0 Test Signal Level = 20 mV Open Drain		1.3		Ω

# STD100NH03L

## ELECTRICAL CHARACTERISTICS (continued)

### SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ $t_r$	Turn-on Delay Time Rise Time	$V_{DD} = 15\text{ V}$ $I_D = 30\text{ A}$ $R_G = 4.7\ \Omega$ $V_{GS} = 10\text{ V}$ (Resistive Load, Figure 3)		16 95		ns ns
$Q_g$ $Q_{gs}$ $Q_{gd}$	Total Gate Charge Source Gate Charge Gate-Drain Charge	$V_{DD} = 15\text{ V}$ $I_D = 60\text{ A}$ $V_{GS} = 10\text{ V}$		57 11.8 7.3	77	nC nC nC
$Q_{oss}^{(6)}$	Output Charge	$V_{DS} = 16\text{ V}$ $V_{GS} = 0\text{ V}$		27		nC
$Q_{gls}^{(7)}$	Third-quadrant Gate Charge	$V_{DS} < 0\text{ V}$ $V_{GS} = 10\text{ V}$		55		nC

### SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(off)}$ $t_f$	Turn-off Delay Time Fall Time	$V_{DD} = 15\text{ V}$ $I_D = 30\text{ A}$ $R_G = 4.7\ \Omega$ , $V_{GS} = 10\text{ V}$ (Resistive Load, Figure 3)		48 23		ns ns

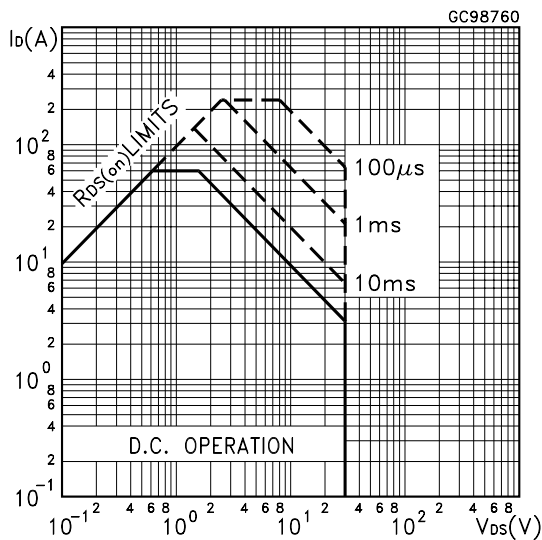
### SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_{SD}$ $I_{SDM}$	Source-drain Current Source-drain Current (pulsed)				60 240	A A
$V_{SD}^{(5)}$	Forward On Voltage	$I_{SD} = 30\text{ A}$ $V_{GS} = 0$			1.4	V
$t_{rr}$ $Q_{rr}$ $I_{RRM}$	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 60\text{ A}$ $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 30\text{ V}$ $T_j = 150^\circ\text{C}$ (see test circuit, Figure 5)		46 64 2.8	62 86	ns nC A

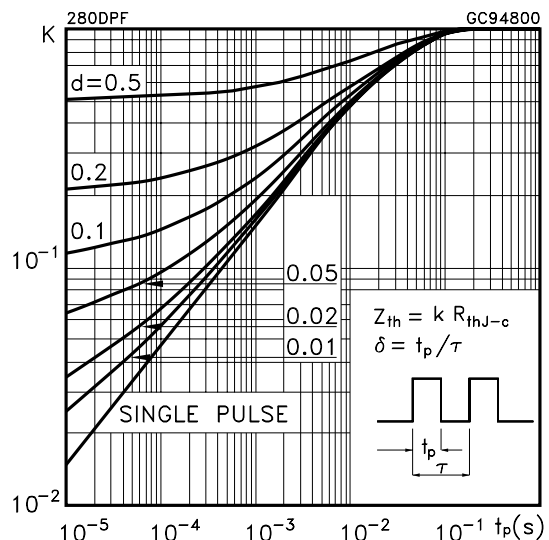
(2) Value limited by wire bonding  
 (3) Pulse width limited by safe operating area.  
 (4) Starting  $T_j = 25^\circ\text{C}$ ,  $I_D = 30\text{A}$ ,  $V_{DD} = 15\text{V}$

(5) Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %.  
 (6)  $Q_{oss} = C_{oss} \cdot \Delta V_{in}$ ,  $C_{oss} = C_{gd} + C_{ds}$ . See Appendix A  
 (7) Gate charge for synchronous operation

### Safe Operating Area

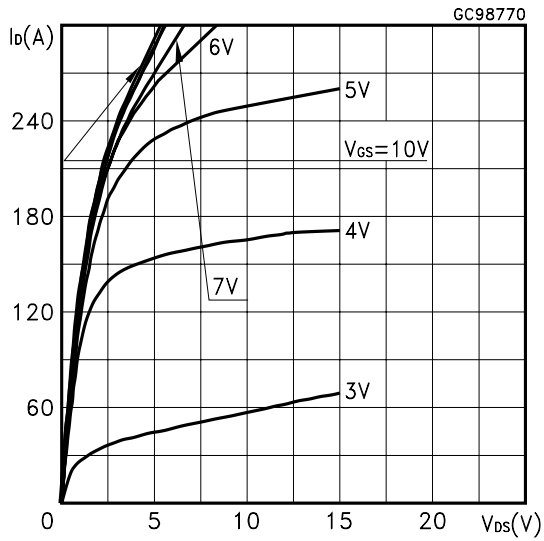


### Thermal Impedance

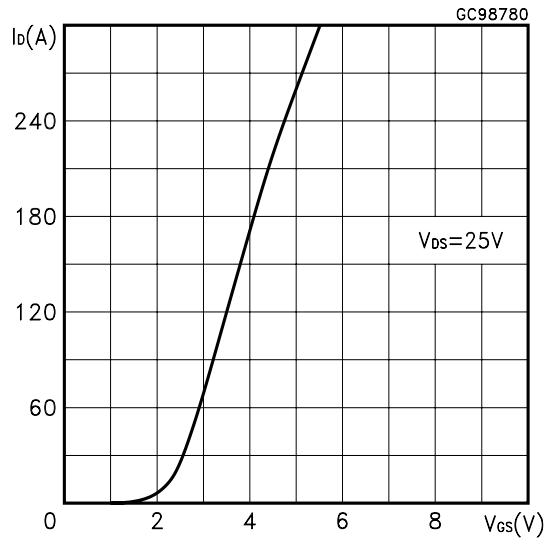


# STD100NH03L

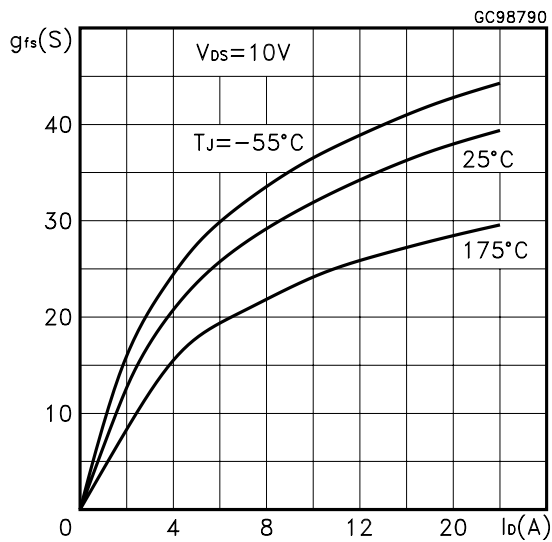
Output Characteristics



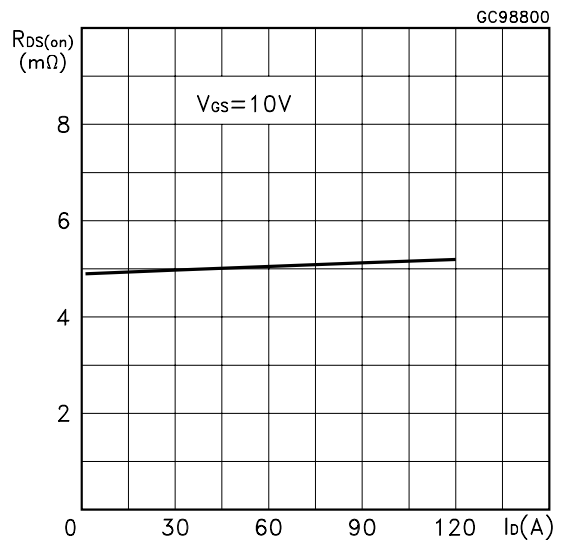
Transfer Characteristics



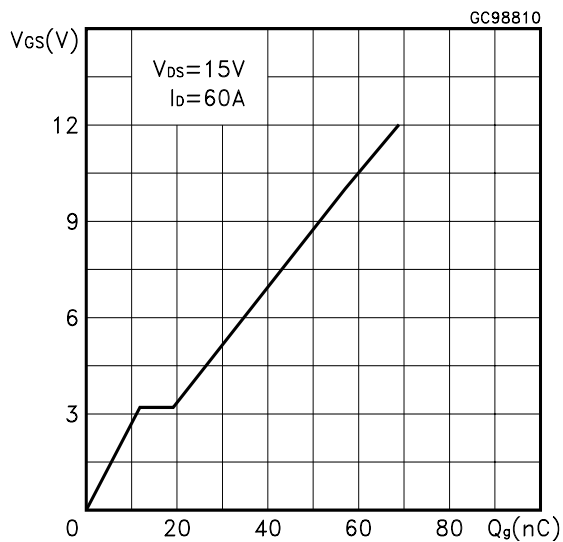
Transconductance



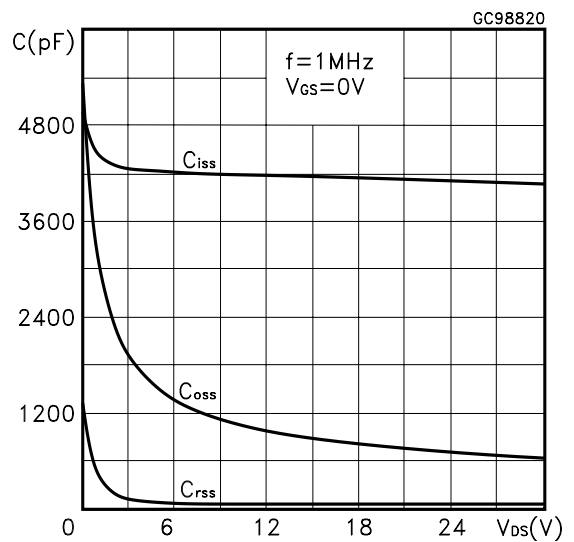
Static Drain-source On Resistance



Gate Charge vs Gate-source Voltage

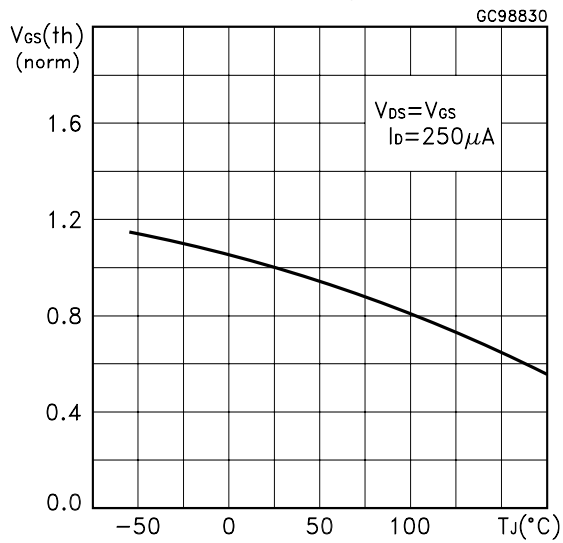


Capacitance Variations

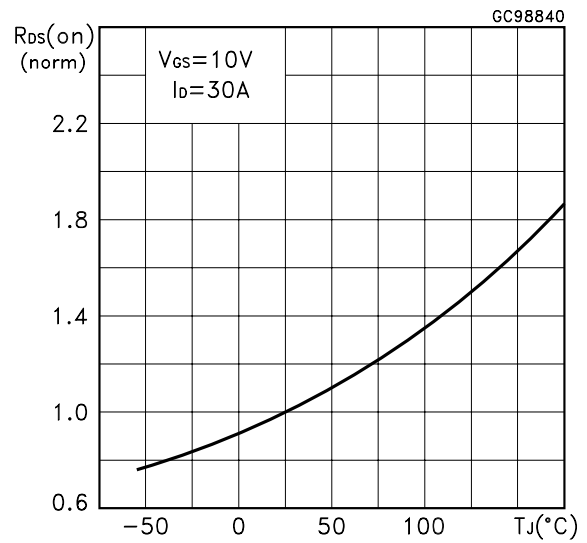


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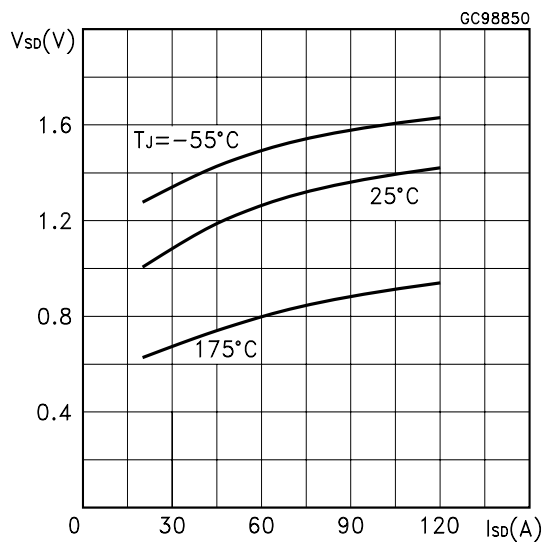
Normalized Gate Threshold Voltage vs Temperature



Normalized on Resistance vs Temperature



Source-drain Diode Forward Characteristics



Normalized Breakdown Voltage vs Temperature

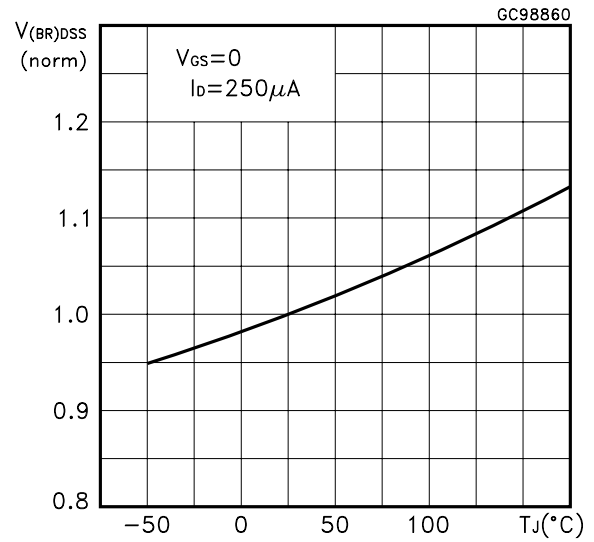


Fig. 1: Unclamped Inductive Load Test Circuit



Fig. 2: Unclamped Inductive Waveform



Fig. 3: Switching Times Test Circuits For Resistive Load



Fig. 4: Gate Charge test Circuit

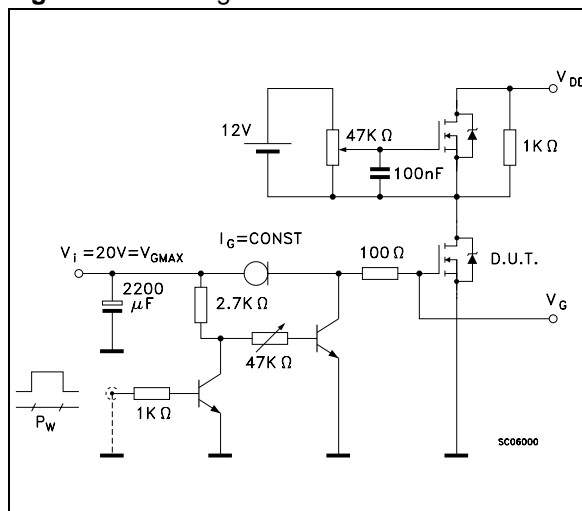
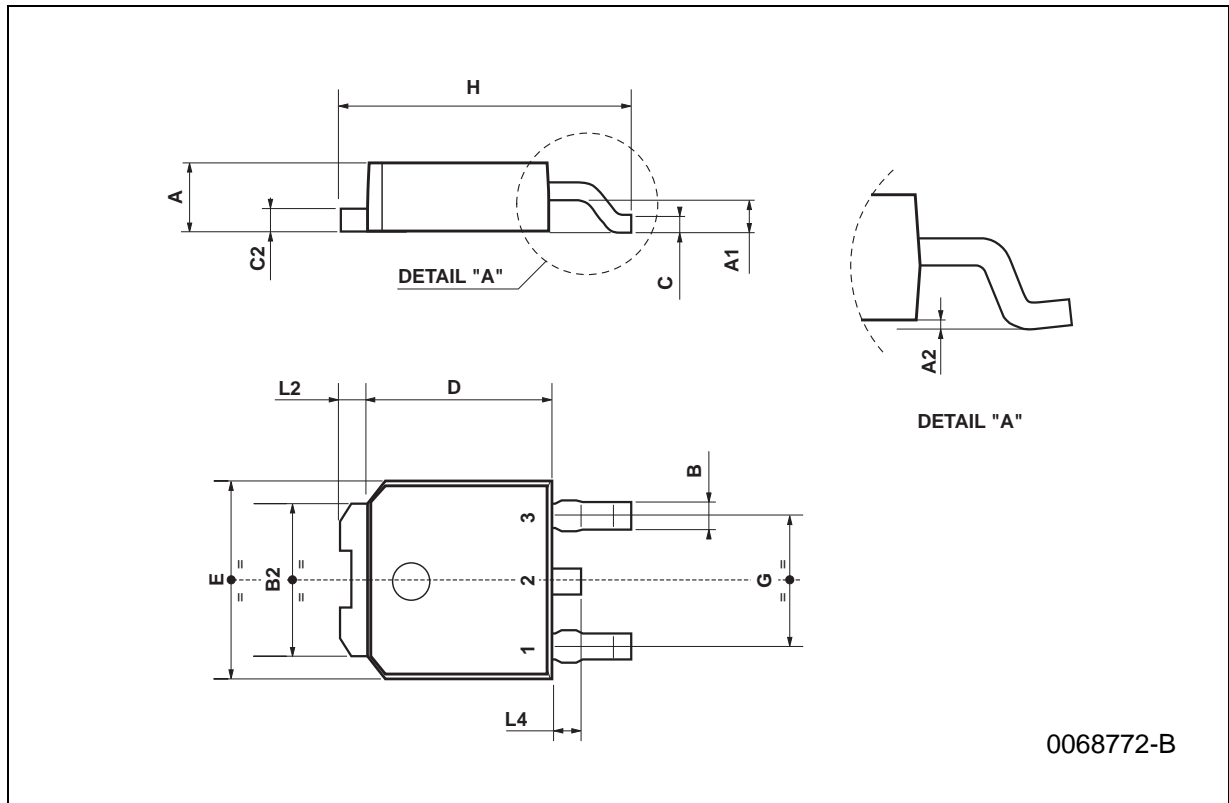


Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times

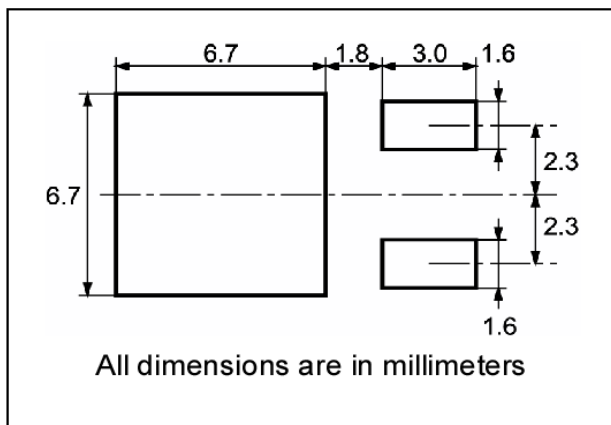


**TO-252 (DPAK) MECHANICAL DATA**

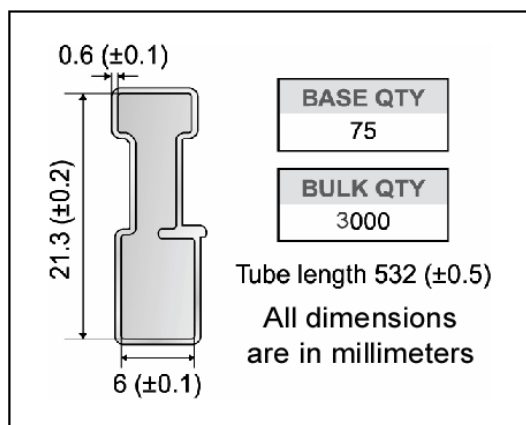
DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	2.2		2.4	0.086		0.094
A1	0.9		1.1	0.035		0.043
A2	0.03		0.23	0.001		0.009
B	0.64		0.9	0.025		0.035
B2	5.2		5.4	0.204		0.212
C	0.45		0.6	0.017		0.023
C2	0.48		0.6	0.019		0.023
D	6		6.2	0.236		0.244
E	6.4		6.6	0.252		0.260
G	4.4		4.6	0.173		0.181
H	9.35		10.1	0.368		0.397
L2		0.8			0.031	
L4	0.6		1	0.023		0.039



**DPAK FOOTPRINT**



**TUBE SHIPMENT (no suffix)\***



**TAPE AND REEL SHIPMENT (suffix "T4")\***

330		12.992
	0.059	
13.2	0.504	0.520
	0.795	
18.4	0.645	0.724
	1.968	
22.4		0.881

40 mm min. Access hole

**REEL MECHANICAL DATA**

A	
B	1.5
C	12.8
D	20.2
G	16.4
N	50
T	

**TAPE MECHANICAL DATA**

DIM.	mm		inch	
	MIN.	MAX.	MIN.	MAX.
A0	6.8	7	0.267	0.275
B0	10.4	10.6	0.409	0.417
B1		12.1		0.476
D	1.5	1.6	0.059	0.063
D1	1.5		0.059	
E	1.65	1.85	0.065	0.073
F	7.4	7.6	0.291	0.299
K0	2.55	2.75	0.100	0.108
P0	3.9	4.1	0.153	0.161

**BASE QTY**

1000
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